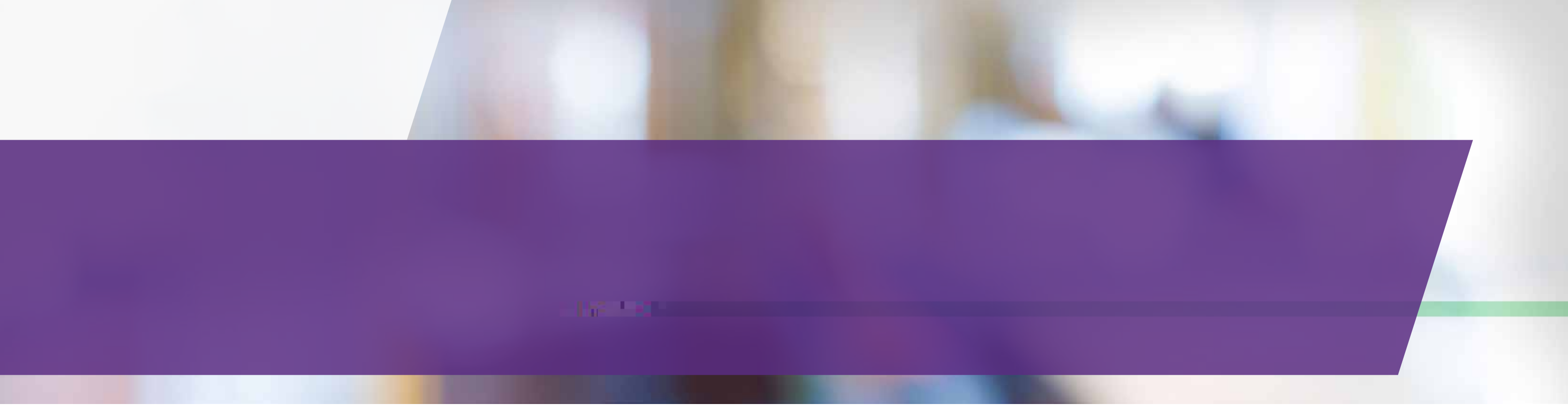


Overview

Benefits

Defect Analysis

Interactive Lot, Wafer and Defect Extraction Reports

Binsort E-Test-Defect Correlation

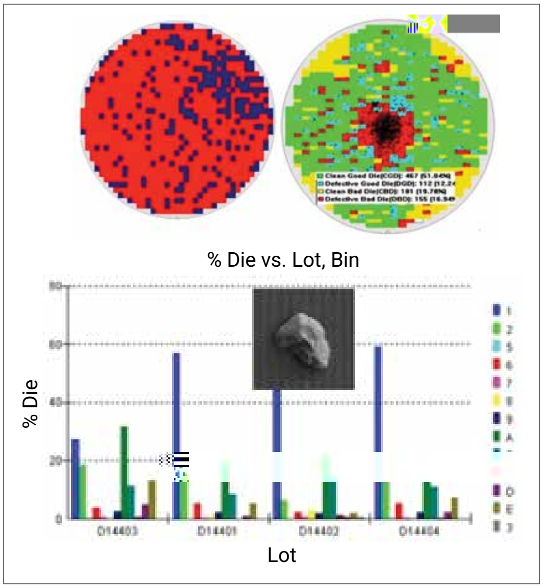
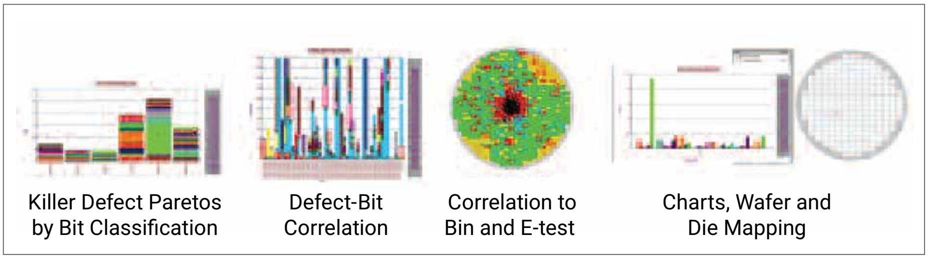


Figure 5: Defect to binsort correlation improves yield monitoring

Enhanced Bitmapping



Killer Defect Paretos by Bit Classification

Defect-Bit Correlation

Correlation to Bin and E-test

Charts, Wafer and Die Mapping

Figure 6: Comprehensive defect bitmap and sort correlation analysis to improve yield monitoring

MES/WIP Analysis

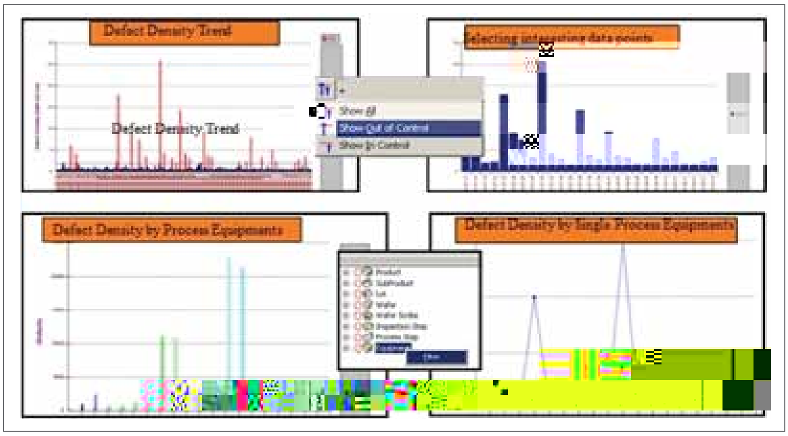

Defect Density Trend
Defect Density Trend
Show All
Show Out of Control
Show In Control
Selecting interesting data points
Defect Density by Process Equipments
Product
SubProduct
Lot
Wafer
Wafer Scribe
Inspection Step
Process Step
Equipment
Defect Density by Single Process Equipments

Figure 7: Typical MES systems include PROMIS™, FACTORYworks™, WorkStream™ and Siview™

Parametric Module

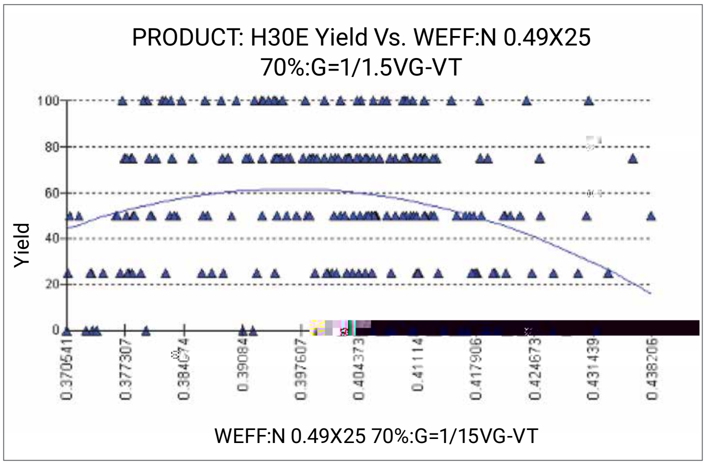


Figure 8: Parametric module imports inline and EOL device performance structures for correlation to die fallout across a wafer or group of wafers